



A F JMW  
Docket No.: M4065.0239/P239  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Larry Hillyer et al.

Application No.: 09/653,561

Art Unit: 2812

Filed: August 31, 2000

Examiner: Ha T. Nguyen

For: METHOD AND MATERIAL FOR  
REMOVING ETCH RESIDUE FROM HIGH  
ASPECT RATIO CONTACT SURFACES

AMENDMENT UNDER 37 C.F.R. § 1.116 IN RESPONSE

TO FINAL OFFICE ACTION

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action mailed November 24, 2004, please amend the above-identified U.S. patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 18 of this paper.